Process Change Notification

PCN Number: PCN-000016 **PCN Notification Date:** March 7th, 2024

Initial PCN

Lead Frame 2nd Source Supplier(s) for 28L TSSOP component material

Dear Customer,

This Initial PCN notification is to advise you of the following change(s):

- Due to on-going supply constraints and overall demand our supply base (ANST) is adding 2nd Source Lead Frame Suppliers (Ningbo Kangqiang Electronics Co., Ltd. and PoongSan (Tongling LanDan Poongsan Microtec Co., Ltd) for the 28L TSSOP component material to ensure continuity of supply.

- There is no anticipated adverse impact to the Fit, Function, Quality and/or Reliability of said product.

  Note: Both identified 2nd Source Suppliers have been well-established / qualified lead frame material supplier of ANST for several years.

A Final PCN is forthcoming and will depict the results of the package level qualification.

Upon successful completion of the package level qualification, the change will be effective immediately. Thereafter, utilization of the 2nd source supplier lead frame material will commence, be a running change through Q2_2024 and fully transition in 2024.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

Quality Systems Administrator
Cirrus Logic Corporate Quality
Phone: +1(512) 851-4000

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Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

Title:	Lead Frame 2nd Source Supplier(s) for 28L TSSOP component material					
Customer Contact:	Local Field Sales Representative	**Phone:**	(512) 851-4000	**Dept:**	Corporate Quality	
Proposed 1st Ship Date:	Q2_2024	**Estimated Sample Availability Date:**		Upon Request		
Change Type:						
	Assembly Site		Assembly Process	X	Assembly Materials	
	Wafer Fab Site		Wafer Fab Process		Wafer Fab Materials	
	Wafer Bump Site		Wafer Bump Process		Wafer Bump Material	
	Test Site		Test Process		Design	
	Electrical Specification		Mechanical Specification		Part Number	
	Packing/Shipping/Labeling	X	Other			
Comments:	Addition of 2nd Source Lead Frame Suppliers					

PCN Details

Description of Change:

Source Change(s):

Addition of 2nd Source Lead Frame Suppliers (Ningbo Kangqiang Electronics Co., Ltd. and PoongSan (Tongling LanDan Poongsan Microtec Co., Ltd.).

Form Change(s):

- Frame Strip Size

From:	59mm * 215.488mm (84 Pads/Strip)	**To:**	75mm*243mm (128 Pads/Strip)

Note: Size for the individual unit remains the same.

- Plating Coverage

From:	Spot Ag	**To:**	Double Ring Ag

Note: Better Mold Compound Adhesion

- Frame Processing Method

From:	Etched	**To:**	Stamped

Note: Better for High Volume Manufacturing

Reason for Change:

To maintain continuity of material supply.

Anticipated Impact on Form, Fit, Function, Quality or Reliability:

There is no anticipated adverse impact to the Fit, Function, Quality and/or Reliability of said product.

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Anticipated Impact on Material Declaration:

☒ No Impact to the Material Declaration

☐ Material Declarations or Product Content reports are driven from production data and will be available following the production release.

Product Affected:

Device	Cirrus Logic Part Number
1	CS8416K-CZZ
2	CS8416K-CZZR
3	CS8416K-DZZ
4	CS8416K-DZZR

Changes To Product Identification Resulting From This PCN:

No change to product identification

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The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

CS8416K - Qualification

CS5490-ISZ Qualification: ☒ **Plan** ☐ **Test Results**			
Reliability Test	**Standard**	**Conditions**	**Sample Size (PASS/FAIL)**
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (3 Lots – 5 units / Lot)	(Results Are Pending)
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (3 Lots – 5 units / Lot)	(Results Are Pending)
SD (Solderability)	JESD22 B102	245°C / 8 hr steam age before SD (3 Lot – 5 units)	(Results Are Pending)
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (30 - Units)	(Results Are Pending)
Pre-Conditioning	JEDEC J-STD-020 JESD22-A113	MSL3 (85℃/85% RH, 168hrs) (3 Lots) – 77 units/Lot	(Results Are Pending)
Temperature Cycle	JESD22 A104	-65°C to +150°C for 500 cycles (3 Lots) – 77 units/Lot	(Results Are Pending)
uHAST (Unbiased HAST)	JESD22 A118	+130℃/85% RH, 96 hrs (3 Lots) – 77 units/Lot	(Results Are Pending)
CSAM	J-STD-035	(3 Lots) – 22 units/Lot	(Results Are Pending)

Notes:

- Successful Qualification Criterion: “pass” on zero fails for each test depicted above.

Reliability Qualification Results:

- (Results Are Pending)